



## Product Change Notification: BLAS-27DYFJ877

### Date:

03-Nov-2025

### Product Category:

Wireless Modules

### Notification Subject:

CCB 7215.002 Final Notice: Qualification of MMT as an additional assembly site for PIC32CX5109BZ36032-E/RTB, PIC32CX5109BZ31032T-V/RTB, PIC32CX5109BZ31032-V/RTB, PIC32CX5109BZ36032T-E/RTB, PIC32CX5109BZ36032T-V/RTB and PIC32CX5109BZ36032-V/RTB catalog part numbers (CPN) available in 32L VQFN (5x5x1mm) package.

### Affected CPNs:

[BLAS-27DYFJ877\\_Affected\\_CPN\\_11032025.pdf](#)

[BLAS-27DYFJ877\\_Affected\\_CPN\\_11032025.csv](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of MMT as an additional assembly site for PIC32CX5109BZ36032-E/RTB, PIC32CX5109BZ31032T-V/RTB, PIC32CX5109BZ31032-V/RTB, PIC32CX5109BZ36032T-E/RTB, PIC32CX5109BZ36032T-V/RTB and PIC32CX5109BZ36032-V/RTB catalog part numbers (CPN) available in 32L VQFN (5x5x1mm) package.

### Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	ASE Group Chung-Li (ASCL)	ASE Group Chung-Li (ASCL)	Microchip Technolo

			gy Thailand (Branch) (MMT)	
<b>Wire Material</b>	CuPdAu	CuPdAu	CuPdAu	No
<b>Die Attach Material</b>	EN4900 (PFAS-free)	EN4900 (PFAS-free)	3280NP (PFAS-free)	Yes
<b>Molding Compound Material</b>	G700LA	G700LA	G700LT D	Yes
<b>Lead-Frame Material</b>	C194	C194	C194	No
<b>Lead-Frame Paddle Size</b>	150x150 mils	150x150 mils	154x154 mils	Yes
<b>DAP Surface Prep</b>	Ag Double Ring	Ag Double Ring	Ag ring with roughening	Yes
<b>Lead-lock</b>	Yes	Yes	Yes	No
See Pre and Post Change Summary for Comparison.				

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve productivity and on-time delivery performance by qualifying MMT as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 20 January 2026 (date code: 2604)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary:**

	November 2025					>	January 2026				
Work Week	44	45	46	47	48		01	02	03	04	05
Qual Report Availability		x									
Final PCN Issue Date		x									
Estimated Implementation Date									x		

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN # Qual Report.

**Revision History:** November 03, 2025: Issued final notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

### Attachments:

[PCN\\_BLAS-27DYFJ877\\_Qual Report.pdf](#)

[PCN\\_BLAS-27DYFJ877\\_Pre\\_and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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